

EKC505™ Cu

EKC Copper Integration Technology

Product Description

EKC505™ Cu is a solvent-based solution designed for complete removal of positive photoresist in the presence of exposed copper. It displays excellent copper and low-k dielectric compatibility.

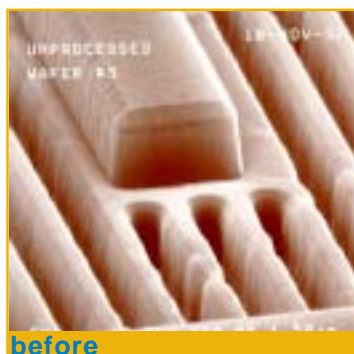
Applications

Used in the removal of positive photoresist from dual damascene structures containing copper and low-k dielectrics.

Product Performance

EKC505™ Cu effectively removes positive photoresist over low-k dielectric materials, while maintaining the structural integrity of the vias. It shows excellent compatibility with copper structures.

“Photoresist removal in the presence of exposed Cu”



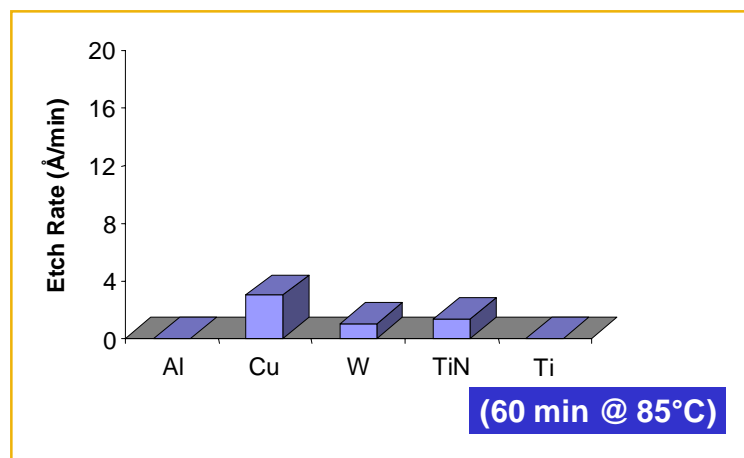
before

TEOS
over Cu



after

Excellent compatibility of
EKC505™ Cu with critical metals



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